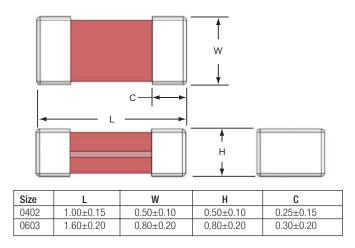
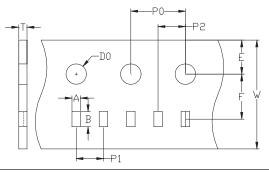
Dimensions - mm

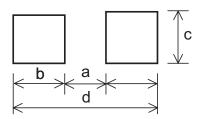


Tape Packaging Specifications - mm



0402 Carrier Dimensions										
Α	В	W	E	F	P0	P1	P2	D0	Т	
0.58 ±0.03	1.2 ±0.03	8.0 ±0.1	1.75 ±0.05	3.5 ±0.05	4.0 ±0.1	2.0 ±0.05	2.0 ±0.05	1.55 ±0.05	0.60 ±0.03	
0603 Carrier Dimensions										
0.90 ±0.20	1.80 ±0.20	8.0 ±0.30	1.75 ±0.10	3.50 ±0.05	4.00 ±0.10	-	2.00 ±0.05	1.50 ±0.10	-	

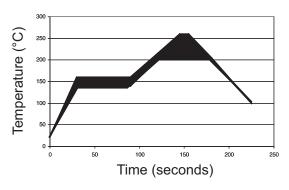
Recommended Pad Layout - mm (in)



Size	а	b	C	d
0402	0.51 (0.020)	0.61 (0.024)	0.51 (0.020)	1.70 (0.067)
0603	0.50 (0.020)	1.02 (0.040)	0.76 (0.030)	2.54 (0.100)

Soldering Recommendations

- · Compatible with lead and lead-free solder reflow processes
- Peak reflow temperatures and durations:
- IR Reflow = 260° C max for 30 sec. max.
- Wave Solder = 260° C max. for 10 sec. max.
- Recommended IR Reflow Profile:



Life Support Policy: Eaton does not authorize the use of any of its products for use in life support devices or systems without the express written approval of an officer of the Company. Life support systems are devices which support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

Eaton reserves the right, without notice, to change design or construction of any products and to discontinue or limit distribution of any products. Eaton also reserves the right to change or update, without notice, any technical information contained in this bulletin.

Eaton

Electronics Division 1000 Eaton Boulevard Cleveland, OH 44122 United States www.eaton.com/electronics

© 2017 Eaton All Rights Reserved Printed in USA Publication No. 4071 BU-SB10744 June 2017

Eaton is a registered trademark.

All other trademarks are property of their respective owners.

Powerina Business Worldwide